

Improve the appearance, content and clarity of the spec.

DOCUMENT CHANGE REQUEST

504 DCR number Changes required for: General Originator: S Jeffery - ESCC Date: 2009/04/28 Date sent: 2009/04/28 Organisation: ESA/ESTEC Status: IMPLEMENTED Title: Transistors High Power NPN, based on type BUX77 Number: 5203/016 Issue: 2 Other documents affected: Page: See attached mark-up of 5203/016 (Issue 3 â.. Draft A). Note that this mark-up also includes the change of DCR 447 (DCR 447 was approved 16th December 2008); it is proposed that once this DCR has been approved, DCR 447 is introduced concurrently. Paragraph: See attached mark-up of 5203/016 (Issue 3 â.. Draft A). Note that this mark-up also includes the change of DCR 447 (DCR 447 was approved 16th December 2008); it is proposed that once this DCR has been approved, DCR 447 is introduced concurrently. Original wording: Proposed wording: To introduce a number of editorial and technical changes (see the attached mark-up) which are required to make this detail spec clear, complete and consistent with the standard format and content of specifications for similar Part Types. Justification:

Attachments:
5203016_Issue_3Draft_A.pdf, null
Modifications:
Page 6: original Note 2 to Maximum Ratings, add ", and any handling,"between "testing" and "performed".
Approval signature:
Horntes
Date signed:
2009-04-28

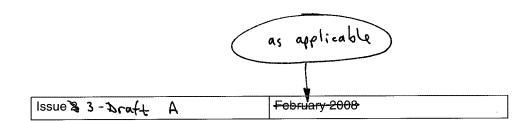


Pages 1 to 16

TRANSISTORS, HIGH POWER, NPN

BASED ON TYPE BUX77

ESCC Detail Specification No. 5203/016







as applicable

PAGE 2
ISSUE \$ 3- braft A

LEGAL DISCLAIMER AND COPYRIGHT

European Space Agency, Copyright © 2008. All rights reserved.

The European Space Agency disclaims any Hability or responsibility, to any person or entity, with respect to any loss or damage caused, or alleged to be caused, directly or indirectly by the use and application of this ESCC publication.

This publication, without the prior permission of the European Space Agency and provided that it is not used for a commercial purpose, may be:

- copied in whole, in any medium, without alteration or modification.
- copied in part, in any medium, provided that the ESCC document identification, comprising the ESCC symbol, document number and document issue, is removed.



PAGE 3

ISSUE & 3 - Draft A

DOCUMENTATION CHANGE NOTICE

(Refer to https://escies.org for ESCC DCR content)

DCR No.	CHANGE DESCRIPTION		
¥87,324	Specification up issued to incorporate editorial and technical changes per	OR _{s.S.}	/
)
447	tbd)		

PAGE 6 ISSUE \$ 3- Draft A

Characteristics	Symbols	Maximum Ratings	Unit	Remarks
Collector-Base Voltage	V _{CBO}	100	V	Over T _{op}
Collector-Emitter Voltage	V _{CEO}	80	V	Over T _{op} Note 4, 3
Emitter-Base Voltage	V _{EBO}	6	٧	Over T _{op}
Collector Current	I _C		Α	Continuous Note 🗛 3
Base Current	Ι _Β	800	mA	Continuous
Power Dissipation	P _{tot}		W	At T _{case} ≤ +25°C
For TO-66 For TO-257		40 35		-
Operating Temperature Range	T _{op}	-65 to +200	°C	Note 🍇 👲
Storage Temperature Range	T _{stg}	-65 to +200	°C	Note 🏖 🚹
Soldering Temperature	T _{sol}	+260	°C	Notes 2
Thermal Resistance, Junction-to-Case For TO-66 For TO-257	R _{th(j-c)}	4.4 5	°C/W	

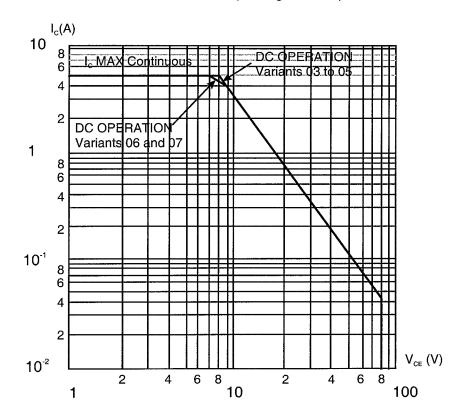
NOTES:

- For T_{case} > +25°C, derate linearly to 0W-at-+200°C.
 For Variants with tin-lead plating or hot solder dip lead finish all testing performed at T_{amb} > +125°C shall be carried out in a 100% inert atmosphere.
- Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the 2.3

same lead shall not be resoldered until 3 minutes have elapsed.

3. Safe Operation Area applies as follows:

Maximum Safe Operating Area Graph



1.6 <u>HANDLING PRECAUTIONS</u>

The TO-257 package contains Beryllium Oxide (BeO) and therefore it must not be ground, machined, sandblasted or subjected to any mechanical operation which will produce dust. The case must not be subjected to any chemical process (e.g. etching) which will produce fumes.

1.7 PHYSICAL DIMENSIONS AND TERMINAL IDENTIFICATION

Consolidated Notes are given following the case drawings and dimensions.

PAGE 14

ISSUE & 3- Braft A

NOTES:

- Read and record measurements shall be performed on a sample of 5 components with 0 failures allowed. Alternatively a 100% inspection may be performed.
- 2. Pulsed measurement: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.

2.6 PARAMETER DRIFT VALUES

Unless otherwise specified, the measurements shall be performed at T_{amb} =+22 $\pm 3^{o}$ C.

The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements.

The drift values (Δ) shall not be exceeded for each characteristic specified. The corresponding absolute limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Limits		Units	
		Drift	Abso	olute	
	基本 基础	Value Δ	Min	Max	
Emitter-Base Cut-off Current	I _{EBO}	±100	-	500	nA
Forward-Current Transfer Ratio 2	h _{FE2}	±25%	50	200	-
Collector-Emitter Saturation Voltage	V _{CE(sat)}	±100	-	1000	mV

2.7 <u>INTERMEDIATE AND END-POINT ELECTRICAL MEASUREMENTS</u>

Unless otherwise specified, the measurements shall be performed at T_{amb} =+22 $\pm 3^{\circ}$ C.

The test methods and test conditions shall be as per the corresponding test defined in Room Temperature Electrical Measurements.

The limit values for each characteristic shall not be exceeded.

Characteristics	Symbols	Lin	Units	
		Min	Max	1.450
Collector-Emitter Cut-off Current	I _{CEO}	-	10	μΑ
Forward-Current Transfer Ratio 2	h _{FE2}	50	200	-
Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	1	V

2.8 POWER BURN-IN CONDITIONS

Characteristics	Symbols	Conditions	Units
Case Temperature	T _{case}	+100 (+0 -5) (1)	°C
Power Dissipation	P _{tot}	As per Maximum Ratings P _{tot}	W
Collector-Emitter Voltage	V _{CE}	10	V

NOTES:

1. No heat sink nor forced air directly on the device shall be permitted.

using the specified Rth(j-c).

Derate



PAGE 16
ISSUE \$ 3 - Draft A

APPENDIX 'A'

AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS		
Deviations from Room Temperature Electrical Measurements	All AC characteristics (Room Temperature Electrical Measurement Note 2) may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes AC characteristic measurements per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.		
Deviations from High and Low Temperatures Electrical Measurements	All characteristics specified may be considered guaranteed but not tested if successful pilot lot testing has been performed on the wafer lot which includes characteristic measurements at high and low temperatures per the Detail Specification. A summary of the pilot lot testing shall be provided if required by the Purchase Order.		
Deviations from Screening Tests - Chart F3	Solderability is not applicable unless specifically stipulated in the Purchase Order.		

(Approved BCR 447 refers)